MOSFET – Power, Single, N-Channel

60 V, 1.2 mΩ, 287 A

NTMFS5C604NL

Features

- Small Footprint (5x6 mm) for Compact Design
- Low R_{DS(on)} to Minimize Conduction Losses
- Low Q_G and Capacitance to Minimize Driver Losses
- These Devices are Pb-Free and are RoHS Compliant

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V _{DSS}	60	V
Gate-to-Source Voltage	€		V _{GS}	±20	V
Continuous Drain		T _C = 25°C	I _D	287	Α
Current R _{θJC} (Notes 1, 3)	Steady	T _C = 100°C		203	
Power Dissipation	State	T _C = 25°C	P _D	200	W
R _{θJC} (Note 1)		T _C = 100°C	1	100	
Continuous Drain		T _A = 25°C	I _D	40	Α
Current R _{θJA} (Notes 1, 2, 3)	Steady State	T _A = 100°C		28	
Power Dissipation		T _A = 25°C	P_{D}	3.9	W
R _{θJA} (Notes 1 & 2)		T _A = 100°C		1.9	
Pulsed Drain Current	$T_A = 25$	°C, t _p = 10 μs	I _{DM}	900	Α
Operating Junction and Storage Temperature			T _J , T _{stg}	-55 to +175	°C
Source Current (Body Diode)			Is	203	Α
Single Pulse Drain-to-Source Avalanche Energy (I _{L(pk)} = 22 A)			E _{AS}	776	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			TL	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case - Steady State	$R_{\theta JC}$	0.75	°C/W
Junction-to-Ambient - Steady State (Note 2)	$R_{\theta JA}$	39	

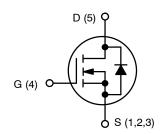
- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 2. Surface-mounted on FR4 board using a 650 mm², 2 oz. Cu pad.
- Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.



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V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX
60 V	1.2 mΩ @ 10 V	287 A
	1.7 mΩ @ 4.5 V	287 A

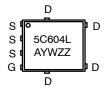


N-CHANNEL MOSFET

MARKING DIAGRAM



DFN5 (SO-8FL) S CASE 506EZ S



5C604L = Specific Device Code A = Assembly Location

Y = Year
W = Work Week
ZZ = Lot Traceability

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS							
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		60			٧
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /				22.9		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V,	T _J = 25°C			10	
		$V_{DS} = 60 \text{ V}$	T _J = 125°C			250	μΑ
Gate-to-Source Leakage Current	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS}$	= 20 V			100	nA
ON CHARACTERISTICS (Note 4)							
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D =$	= 250 μA	1.2		2.0	V
Threshold Temperature Coefficient	V _{GS(TH)} /T _J				-5.9		mV/°C
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 50 A		0.93	1.2	
		V _{GS} = 4.5 V	I _D = 50 A		1.25	1.7	mΩ
Forward Transconductance	9FS	V _{DS} = 15 V, I _D	= 50 A		180		S
Gate Resistance	R_{G}	T _A = 25°C				3.4	Ω
CHARGES AND CAPACITANCES						•	•
Input Capacitance	C _{ISS}	V _{GS} = 0 V, f = 1 MHz, V _{DS} = 25 V			8900		pF
Output Capacitance	C _{OSS}				3750		
Reverse Transfer Capacitance	C _{RSS}				40		-
Total Gate Charge	Q _{G(TOT)}	V _{GS} = 4.5 V, V _{DS} = 30 V; I _D = 50 A			52		
Total Gate Charge	Q _{G(TOT)}	V _{GS} = 10 V, V _{DS} = 30 V; I _D = 50 A			120		1
Threshold Gate Charge	Q _{G(TH)}	V _{GS} = 4.5 V, V _{DS} = 30 V; I _D = 50 A			6.4		nC
Gate-to-Source Charge	Q _{GS}				21.4		
Gate-to-Drain Charge	Q_{GD}				12.7		
Plateau Voltage	V_{GP}				2.8		V
SWITCHING CHARACTERISTICS (Note 5)						•	•
Turn-On Delay Time	t _{d(ON)}	$V_{GS} = 4.5 \text{ V}, V_{DS} = 30 \text{ V},$ $I_{D} = 50 \text{ A}, R_{G} = 2.5 \Omega$			32.9		
Rise Time	t _r				29.9		ns
Turn-Off Delay Time	t _{d(OFF)}				60.3		
Fall Time	t _f				25.2		
DRAIN-SOURCE DIODE CHARACTERISTIC	cs						•
Forward Diode Voltage	V_{SD}	V _{GS} = 0 V,	T _J = 25°C		0.78	1.2	V
		I _S = 50 A	T _J = 125°C		0.64		
Reverse Recovery Time	t _{RR}	V_{GS} = 0 V, dIS/dt = 100 A/ μ s, I _S = 50 A			98		
Charge Time	t _a				45		ns
Discharge Time	t _b				53		1
Reverse Recovery Charge	Q _{RR}				190		nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

^{4.} Pulse Test: pulse width \leq 300 μ s, duty cycle \leq 2%. 5. Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS

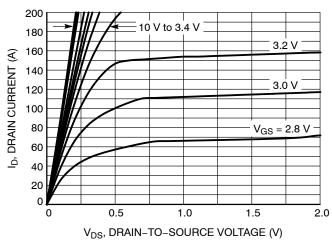


Figure 1. On-Region Characteristics

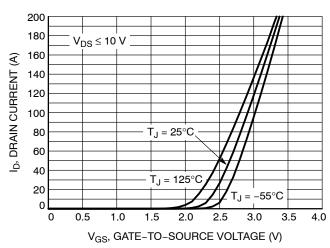


Figure 2. Transfer Characteristics

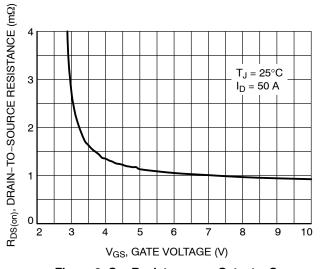


Figure 3. On-Resistance vs. Gate-to-Source Voltage

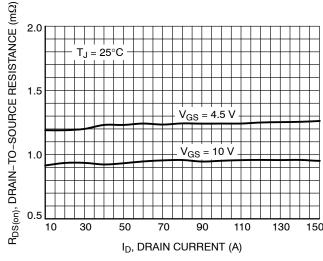


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

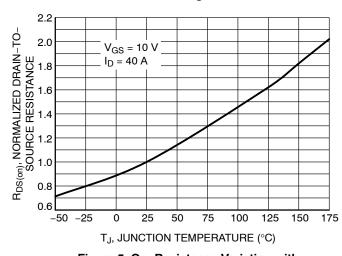


Figure 5. On–Resistance Variation with Temperature

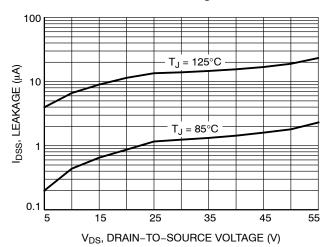
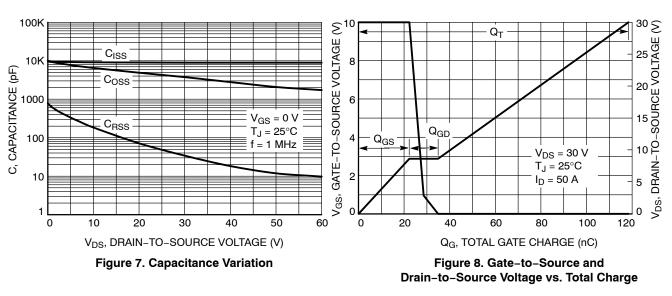


Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL CHARACTERISTICS



100

1000

| Total Control Control

Figure 9. Resistive Switching Time Variation vs. Gate Resistance

10

 R_G , GATE RESISTANCE (Ω)

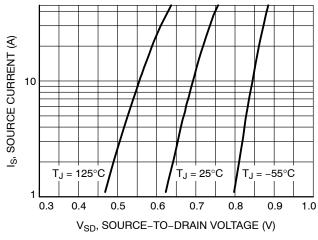


Figure 10. Diode Forward Voltage vs. Current

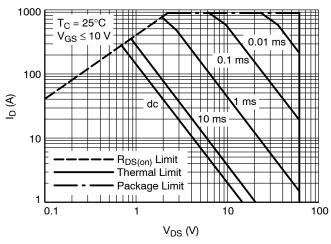


Figure 11. Safe Operating Area

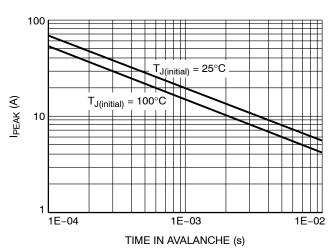


Figure 12. I_{PEAK} vs. Time in Avalanche

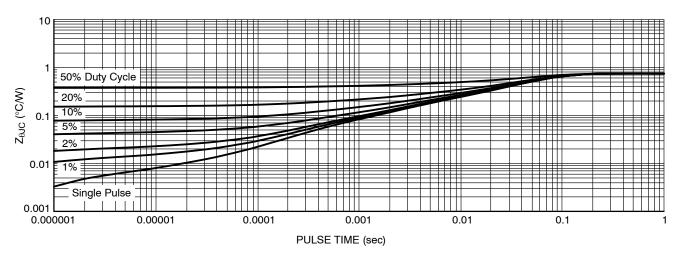


Figure 13. Thermal Characteristics

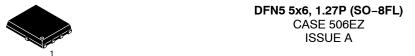
DEVICE ORDERING INFORMATION

Device	Marking	Package	Shipping [†]
NTMFS5C604NLT1G	5C604L	DFN5 (Pb-Free)	1500 / Tape & Reel
NTMFS5C604NLT3G	5C604L	DFN5 (Pb-Free)	5000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

SCALE 2:1





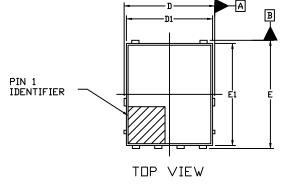
DATE 25 AUG 2021

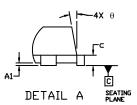
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
 2. CONTROLLING DIMENSION: MILLIMETERS
 3. DIMENSIONS DI AND EI DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

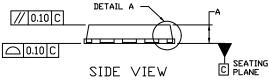
		MI	LLIMETE	25	
	DIM	MIN.	N□M.	MAX.	
-4X θ	Α	0.90	1.00	1.10	
	A1	0.00		0.05	
\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	b	0.33	0.41	0.51	
	С	0.23	0.28	0.33	
t Y	D	5.00	5.15	5.30	
DETAIL A SEATING PLANE	D1	4.70	4.90	5.10	
FLANE	D2	3.80	4.00	4.20	
	Е	6.00	6.15	6.30	
	E1	5.70	5.90	6.10	
	E2	3.45	3.80	3.85	
	е	1.27 BSC			
i	G	0.51	0.575	0.71	
	k	1.10	1.20	1.40	
	L	0.51	0.575	0.71	
	L1		0.125 RE	F	
	М	3.00	3.40	3.80	
	θ	0*		12*	
2X (0.4950 	4.5	56 		

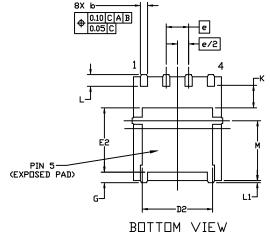
2X 0.25

2X 0.91











PACKAGE DUTLINE





For additional information on our Pb-Free strategy and soldering details, please download the IN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

XXXXXX = Specific Device Code = Assembly Location

Α Υ = Year

W = Work Week

ZZ = Lot Traceability

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■" may or may not be present. Some products may not follow the Generic Marking.

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